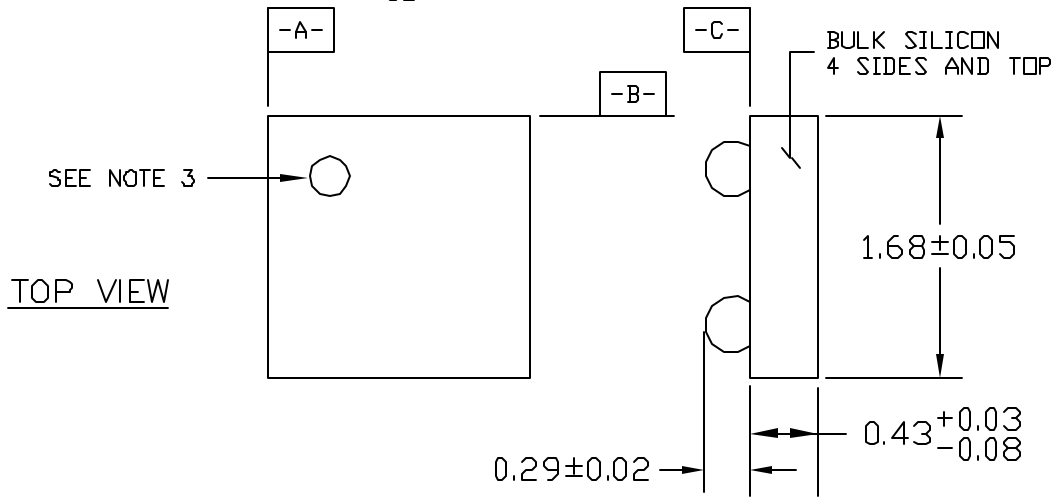
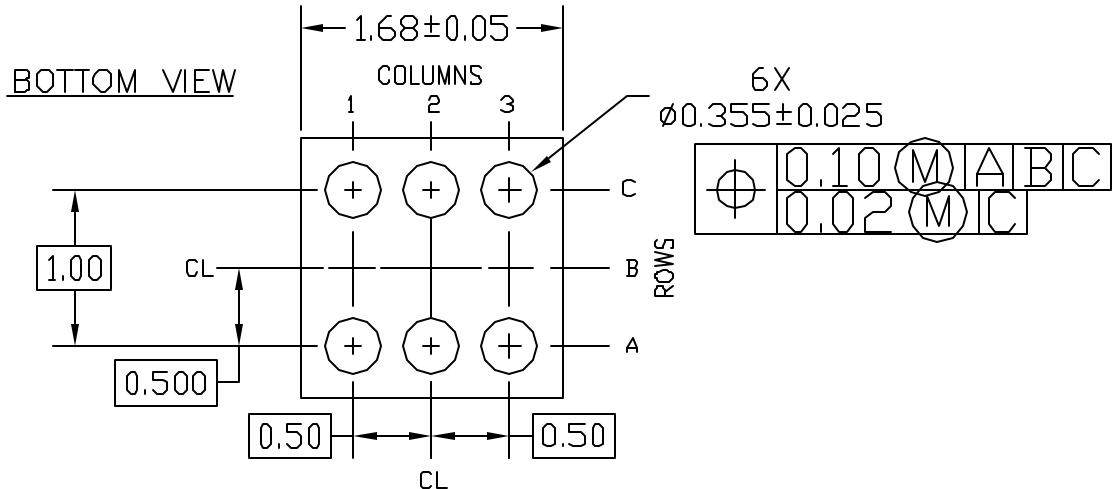


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ORIGINAL ISSUE PER ECN 40875		
B	CHANGE TITLE FROM BF622-1 TO BR622-1	3/07	LWC

NOTES:

1. DIMENSIONS: MM
2. BUMP MATERIAL: 63 Sn / 37 Pb (EUTECTIC)
3. LASER MARK INDICATING A1 CORNER ORIENTATION. NUMBER OF CHARACTERS AND LINES VARY BY PRODUCT.
4. ELECTRICAL NODES -- SEE PRODUCT DATA SHEET OR PROBE DOCUMENT
5. DEPOPULATED SOLDER BALLS: B1, B2, B3



SIGNATURE		DATE		 Dallas Semiconductor PACKAGE OUTLINE, 0.50 MM GRID 3X3 BALL ARRAY USED ON DS2431 PACKAGE CODE: BR622-1			
QA APVD:							
ENGR MGR:							
ENGR BY:				SIZE	FSCM NO.	DWG NO.	REV
CHECK BY:				A		56-G7007-001	B
DRAWN BY:		B. MCCARTY 6/8/04		SCALE		NONE	SHEET 1